

ABSTRACT

The present disclosure provides a flip-chip bonding equipment including a chip transfer mechanism which includes a mounting portion and a driving portion for driving the mounting portion to move, the mounting portion includes a plurality of working positions for placing the chips, wherein by a movement of the mounting portion, a chip placed on one of the working positions is transferred from a first position to a second position; a first chip picking mechanism for flipping the chip from downside toward upside, and placing the flipped chip on the working position at the first position of the mounting portion; a second chip picking mechanism picks up the chip placed at the second position of the mounting portion and performs a chip bonding process. The present disclosure uses a precise chip transfer mechanism, which provides a high reliability and enables the flip-chip bonding equipment to perform the flip-chip bonding for large size substrates without reducing efficiency. Thus, loading accuracy of the flip-chip bonding equipment is greatly improved.

Figure 1 for publication